



Material Content Data Sheet



Sales Product Name		SGD02N60		Issued		20. July 2018		
MA#		MA000269720						
Package		PG-TO252-3-11		Weight*		363.70 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.871	0.24	0.24	2395	2395
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		178	
	non noble metal	iron	7439-89-6	0.215	0.06		592	
	non noble metal	copper	7440-50-8	215.017	59.10	59.18	591191	591961
	non noble metal	aluminium	7429-90-5	0.509	0.14	0.14	1400	1400
wire	non noble metal	aluminium	7429-90-5	0.509	0.14	0.14	1400	1400
encapsulation	organic material	carbon black	1333-86-4	1.230	0.34		3382	
	inorganic material	antimonytrioxide	1309-64-4	2.460	0.68		6765	
	plastics	brominated resin	-	2.460	0.68		6765	
	plastics	epoxy resin	-	24.603	6.76		67647	
	inorganic material	silicondioxide	60676-86-0	92.263	25.37	33.83	253677	338236
leadfinish	non noble metal	tin	7440-31-5	3.740	1.03	1.03	10283	10283
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	250	251
solder	non noble metal	tin	7440-31-5	0.019	0.01		54	
	noble metal	silver	7440-22-4	0.024	0.01		67	
	non noble metal	lead	7439-92-1	0.930	0.26	0.28	2556	2677
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		16	
	non noble metal	iron	7439-89-6	0.019	0.01		53	
	non noble metal	copper	7440-50-8	19.177	5.27	5.28	52728	52797
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com